

Title (en)
System of printed circuit boards

Title (de)
System von Leiterplatten

Title (fr)
Système de circuits imprimés

Publication
EP 0627797 B1 19981125 (EN)

Application
EP 94201555 A 19940603

Priority
NL 9300970 A 19930604

Abstract (en)
[origin: EP0627797A1] Method for manufacturing contact elements from a strip of conductive material, wherein successive contact elements are formed in the strip by cutting away parts between the successive contact elements. Each contact element is made with a contact means with opposite contact faces for contacting a complementary contact element. The contact means of each contact element includes a twisted portion in such a manner that the contact means is twisted along an angle of substantially 90 DEG with respect to the plane of the material strip. <IMAGE>

IPC 1-7
H01R 43/16; **H01R 9/09**

IPC 8 full level
H01R 43/16 (2006.01)

CPC (source: EP)
H01R 43/16 (2013.01); **H01R 12/585** (2013.01)

Cited by
EP1429429A1; EP0793303A3; EP1786074A1; US6848955B2

Designated contracting state (EPC)
BE FR SE

DOCDB simple family (publication)
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